

PRODUCT NUMBER

77317-YXX-XXLF

WHEN REQUIRED, ADD SUFFIX LETTER "LF"
INDICATES THE PRODUCT IS RoHS
COMPATIBLE, SEE NOTE 7

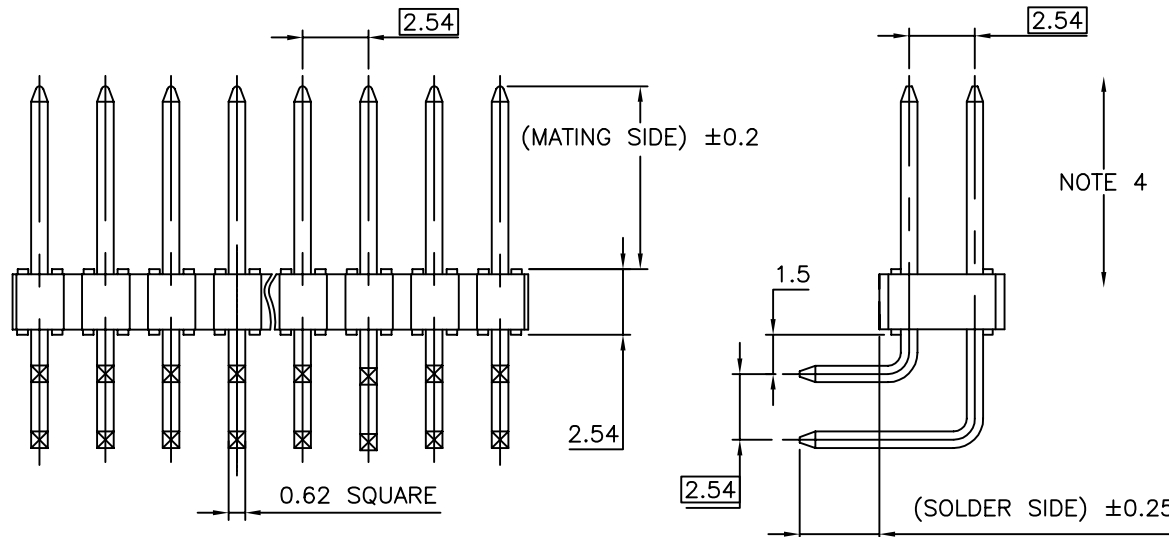
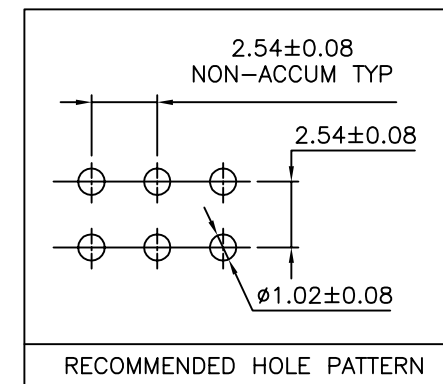
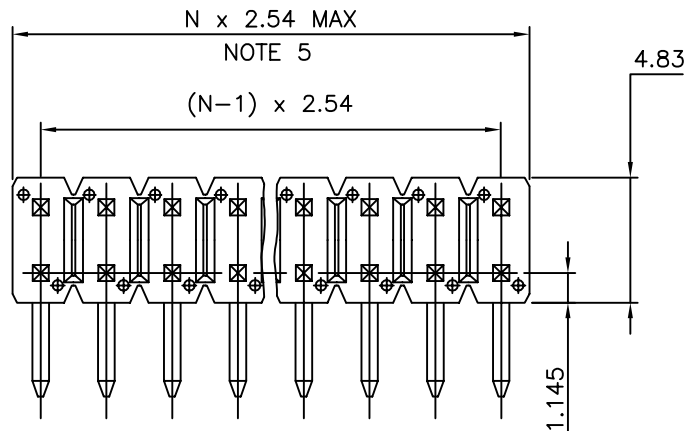
TOTAL NB OF POSITIONS 04 TO 72

PIN STYLE SEE SHEET 2

PLATING SEE SHEET 2

NOTES:

1. HOUSING MAT'L : HIGH TEMPERATURE THERMOPLASTIC. UL94V-0 COLOR: BLACK
2. PIN MATERIAL : PHOSPHOR BRONZE
3. PRODUCT PACKAGED IN POLY BAGS.
4. 9N MIN RETENTION IN EITHER DIRECTION
5. TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS $N \times 2.54 = 20.32\text{mm}$
6. UNDERPLATING : $1.27\mu\text{m}$ Ni MIN
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS
 - a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE, $2\mu\text{m}$ MINIMUM MATTE TIN OVER $1.27\mu\text{m}$ MINIMUM NICKEL UNDERPLATE.
 - b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO $260^\circ\text{C} \pm 5^\circ\text{C}$ SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - c - LABELING:
 - MEETS PACKAGING SPECS AS PER GS-14-920
 - d - LEGAL STATEMENT: SEE GS-22-008



mat'l. code SEE NOTES				tolerances unless otherwise specified		CUSTOMER COPY		F C I ELECTRONICS www.fciconnect.com	
ltr	ecn	no	dr	date				title	
AA	F04-0167	JCO		04.04.05	linear	.X ±0.3	projection	UNSHR.HEADER	
AB	F04-0362	LMU		04.11.29		.XX ±0.15		RA DR TMT	
					angles	.XXX ±0.05			
V	F10306	LMU	01.05.21	dr	D.LE	01.01.24	mm	product family	BERGSTIK
W	F20353	LMU	02.06.18	eng	JM.C	01.01.24		code	213
X	F20592	JCO	02.11.26	chr	JM.C	01.01.24	scale	sheet	1 of 2
Y	F04-0129	LMU	04.02.04	appd	JF.N	01.01.24	5:1	size	77317
sheet	revision	AB	X						
index	sheet	1	2						

CATALOGUE RANGE

PLATING	PIN STYLE	MATING	SOLDER
1/4/8	03	5.84	2.54
1/4/8	04	5.84	3.05
1/4/8	12	6.8	3.05

PLATING

- 1 = 0.76µm GOLD ON CONTACT AREA
3.81µm TIN-LEAD ON TAIL
- 4 = 3.81µm TIN-LEAD ON CONTACT AREA
AND ON TAIL
- 8 = 0.38µm GOLD ON CONTACT AREA
3.81µm TIN-LEAD ON TAIL
- WHEN "LF" IS REQUIRED, 2µm MATTE
TIN OVER 1.27µm MIN NICKEL IS
PROVIDED INSTEAD OF TIN-LEAD

APPLICATION SPECIFIC

PLATING	PIN STYLE	MATING	SOLDER
1/4/8	01	5.72	2.57
1/4/8	14	10	2.7
1/4/8	15	7	16.4
1/4/8	16	7.8	13.5
1/4/8	17	7.48	1.6

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B

A


B

C

C

D

D

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 ELECTRONICS www.fciconnect.com	
ltr	ecn no	dr	date	linear			projection		title	
S	F00141	LMU	00.02.28						UNSHR.HEADER	
T	F10119	DLE	01.01.24						RA DR TMT	
U	F10183	LMU	01.03.30	angles					product family	
V	F20353	LMU	02.06.18	dr	D.LE	01.01.24	mm		BERGSTIK	
W	F20592	JCO	02.11.26	engr	JM.C	01.01.24			code	
X	F04-0362	LMU	04.11.29	chr	JM.C	01.01.24	scale		size	
				appd	JF.N	01.01.24	N/A		dwg no	
sheet	revision								A3	
index	sheet								77317	
									213	
									sheet	
									2 of -	